# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

HP V270 Display

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm, Main Board<em>1, Power Board</em>1, Key pad Board*1</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power board(C816)</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>HDMI cable<em>1, Power cord</em>1, All are inside monitor carton box</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components and waste containing asbestos | 0
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cross screwdriver</td>
<td></td>
</tr>
<tr>
<td>Hexagon screwdriver</td>
<td></td>
</tr>
<tr>
<td>Opening plastic picks</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Press tenon on the rear cover and remove stand, then relief base tenon to separate base and stand.
2. Unscrew rear cover and downside screws, then remove rear cover with opening plastic picks.
3. Remove Key pad PCB/panel power wire/FFC by hand and unscrews metal casing screws with Cross screwdriver.
4. Unscrew PCB board and I/O port screws by cross screwdriver and hexagon screwdriver.
5. Remove Alu tape, acetate tape and Milar sheet from metal casing by hand.
6. Remove internal wire from main PCB board, remove FFC wire by hand.
7. Remove front metal bezel with opening plastic picks.
8. Unscrew base metal screws by screwdriver and separate base metal and base plastic, unscrew hinge screws by screwdriver.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Press tenon on the rear cover and remove stand, then relief base tenon to separate base and stand.

2. unscrew rear cover and downside screws, then remove rear cover with opening plastic picks
3. Remove Key pad PCB/panel power wire/FFC by hand and unscrews metal casing screws with Cross screwdriver.

4. Unscrew PCB board and I/O port screws by cross screwdriver and hexagon screwdriver.
5. Remove Alu tape, acetate tape and Milar sheet from metal casing by hand

6. Remove internal wire from main PCB board, remove FFC wire by hand

7. Remove front metal bezel with opening plastic picks
8. Unscrew base metal screws by screwdriver and separate base metal and base plastic, unscrew hinge screws by screwdriver.